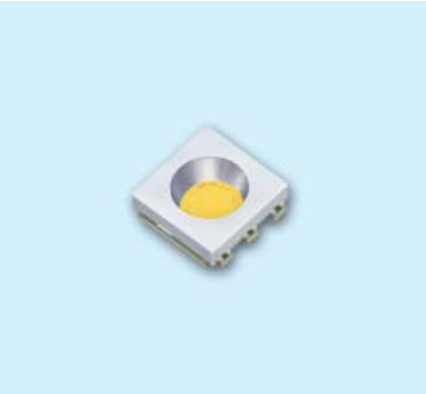
EVERLIGHT ELECTRONICS CO.,LTD.

Technical Data Sheet

Luminosity white Color LED

59-14 UTD/TR8



Features

- Super luminosity white LED.
- Built in 4 LED chips.
- Wide viewing angle.
- Soldering methods: Reflow soldering.
- High performance.
- Package in 12mm tape on 7″ diameter reel.
- Pb-free.
- The product itself will remain within RoHS compliant version.

Descriptions

- The 59-14 SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

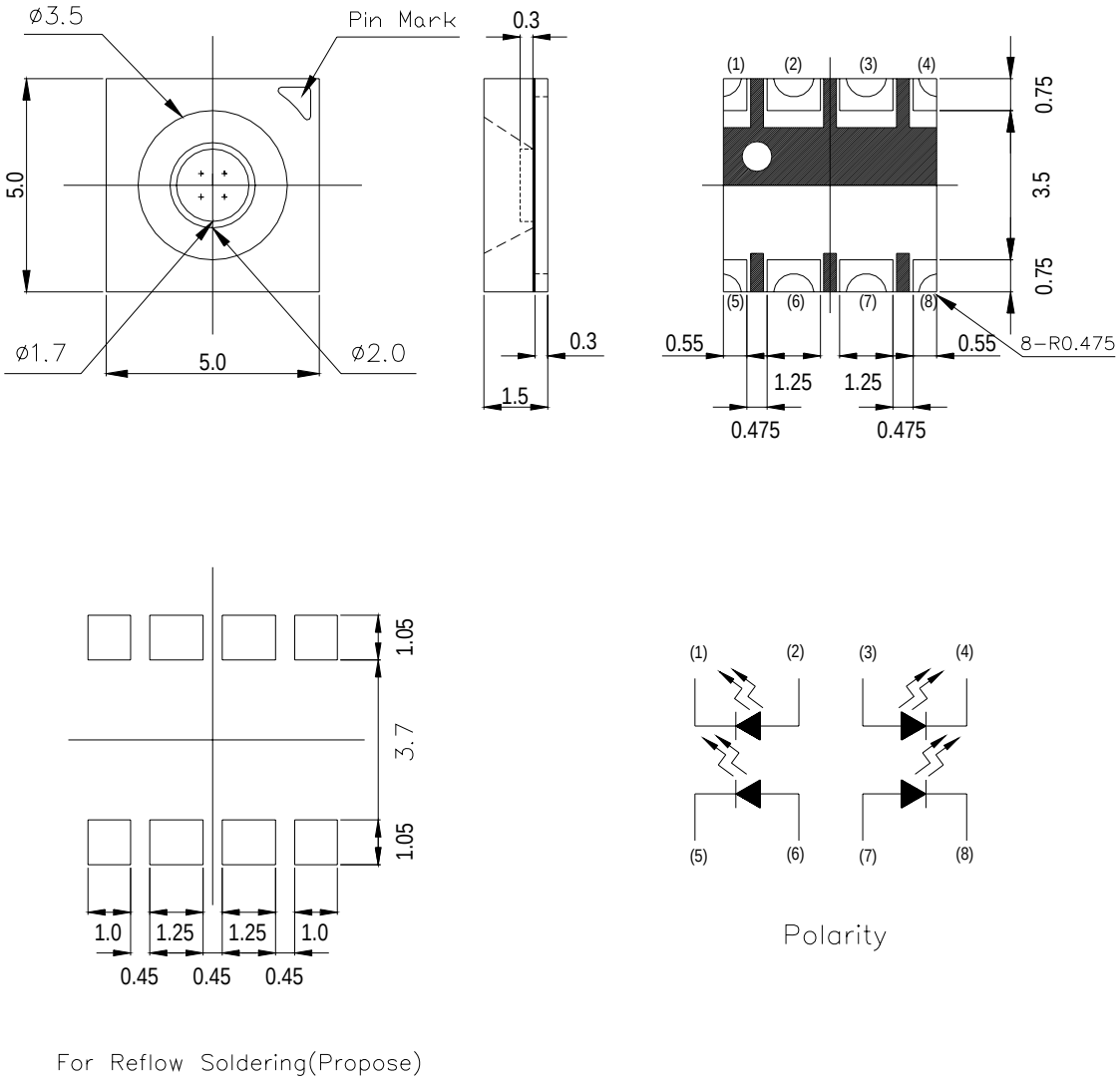
Applications

- Amusement equipment.
- Information boards.
- Flashlight for digital camera of cellular phone.
- Lighting for small size device.

Device Selection Guide

Chip		Lens Color
Material	Emitted Color	
InGaN	White	Yellow diffused

Package Outline Dimensions



Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +90	℃
Electrostatic Discharge(HBM)	ESD	1000	V
Power Dissipation	Pd	110	mW
Peak Forward Current (Duty 1/10 @ 400ms)	I_{FP}	100	mA
Soldering Temperature	Tsol	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

* The value are base d on the 1-die performance.

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity*1	Iv	5.0	8.5	15.0	cd	I_F=20mA*2
		10.0	25.0	45.0		I_{FP}=100mA*2 (Duty 1/10 @ 400ms)
Viewing Angle*1	$2\theta_{1/2}$	-----	60	-----	deg	I_F=20mA*2
Forward Voltage*2	V_F	2.7	3.3	3.7	V	I_F=20mA*2
Forward Voltage*2		3.6	4.4	5.2		I_{FP}=100mA*2 (Duty 1/10 @ 400ms)
Reverse Current*2	I_R	-----	-----	50	μA	V_R=5V*2

*1 When 4 LED dies are operated simultaneously.

*2 For each die.

Note: The products are sensitive to static electricity and care must be fully taken when handling products.

Color Ranks

	Rank A0			
x	0.280	0.264	0.283	0.296
y	0.248	0.267	0.305	0.276

	Rank B3			
x	0.287	0.283	0.304	0.307
y	0.295	0.305	0.330	0.315

	Rank B4			
x	0.307	0.304	0.330	0.330
y	0.315	0.330	0.360	0.339

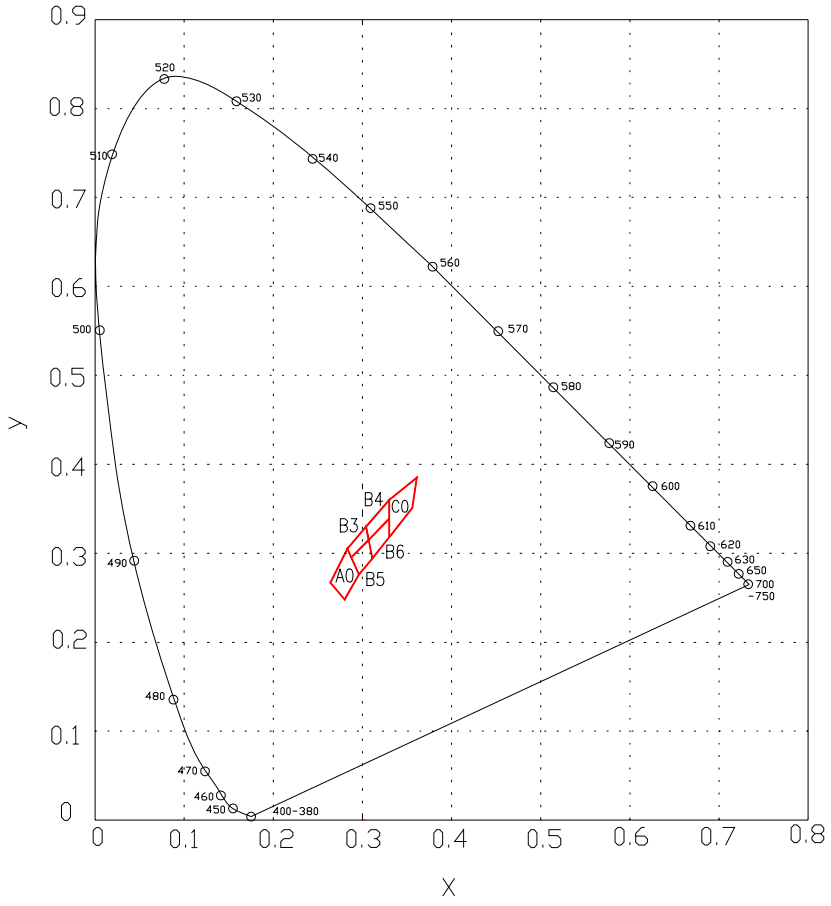
	Rank B5			
x	0.296	0.287	0.307	0.311
y	0.276	0.295	0.315	0.294

	Rank B6			
x	0.311	0.307	0.330	0.330
y	0.294	0.315	0.339	0.318

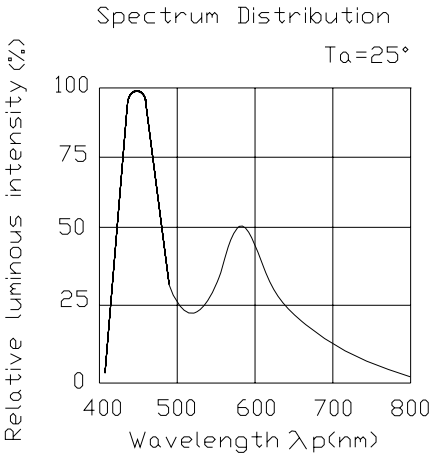
	Rank C0			
x	0.330	0.330	0.361	0.356
y	0.318	0.360	0.385	0.351

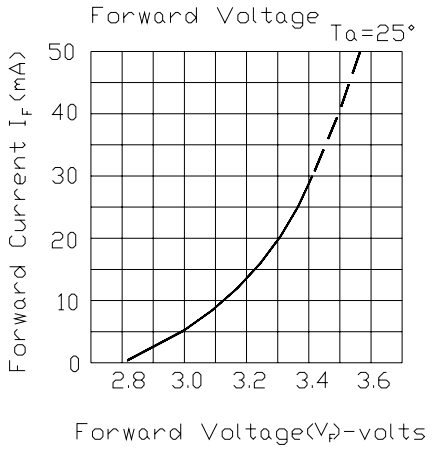
*The C.I.E. 1931 chromaticity diagram (Tolerance ±0.01).

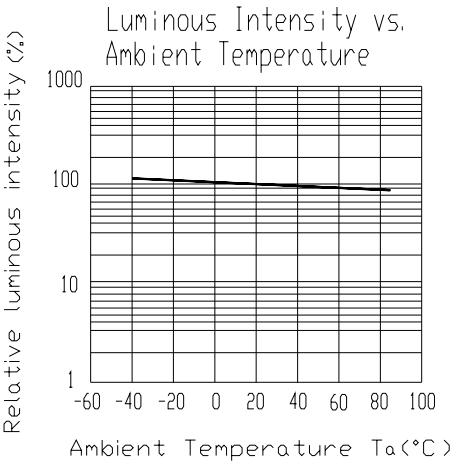
CIE Chromaticity Diagram

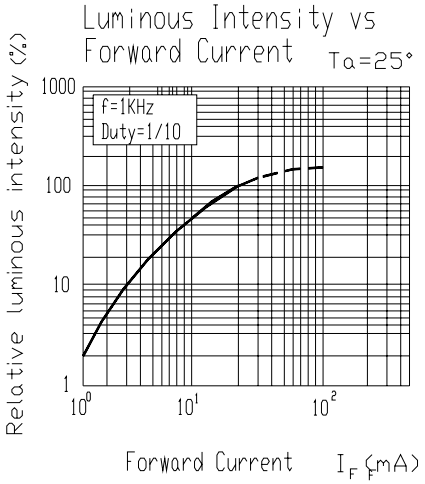


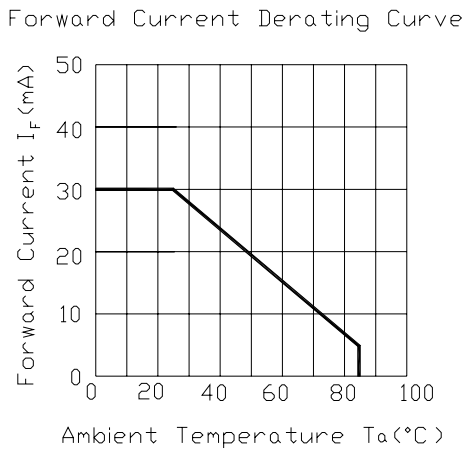
Typical Electro-Optical Characteristics Curves

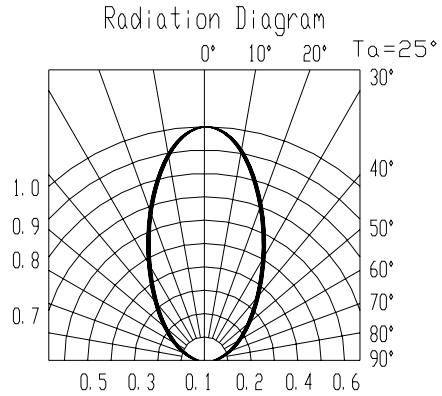






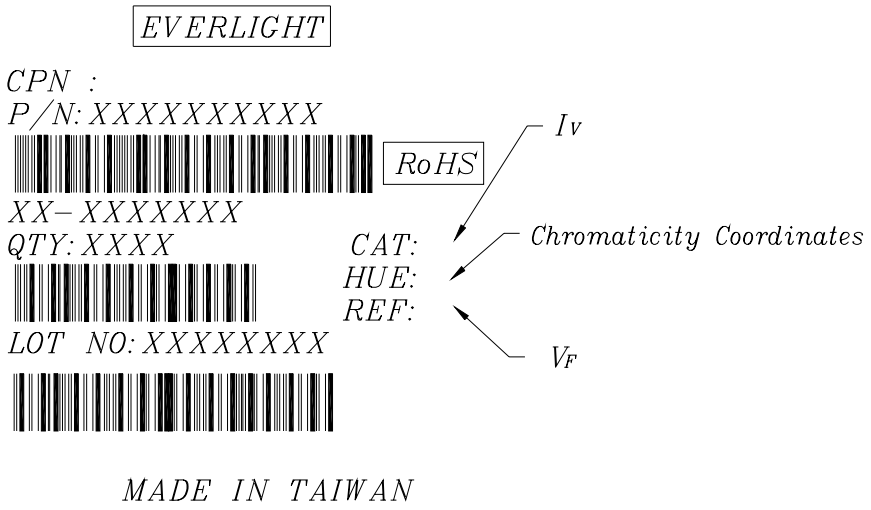




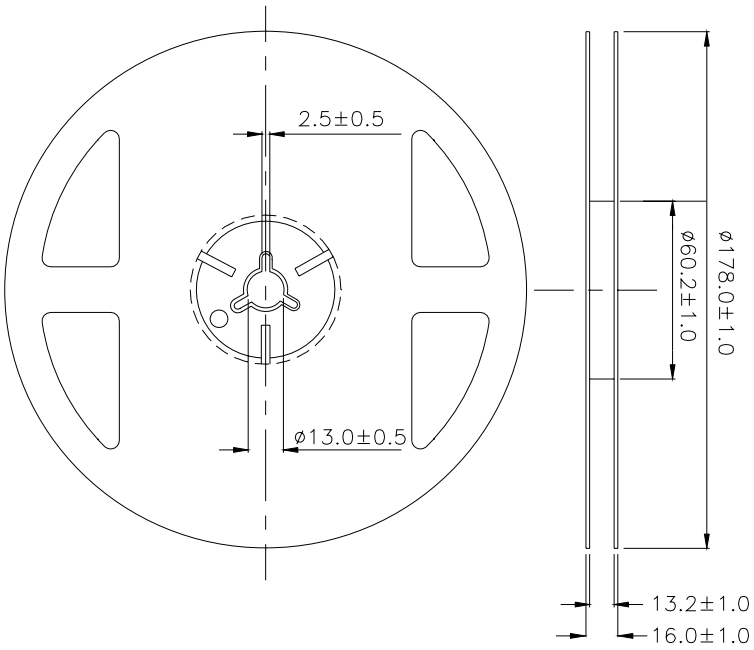


Label explanation

CAT: Luminous Intensity Rank HUE: Chromaticity Coordinates REF: Forward Voltage Rank



Reel Dimensions



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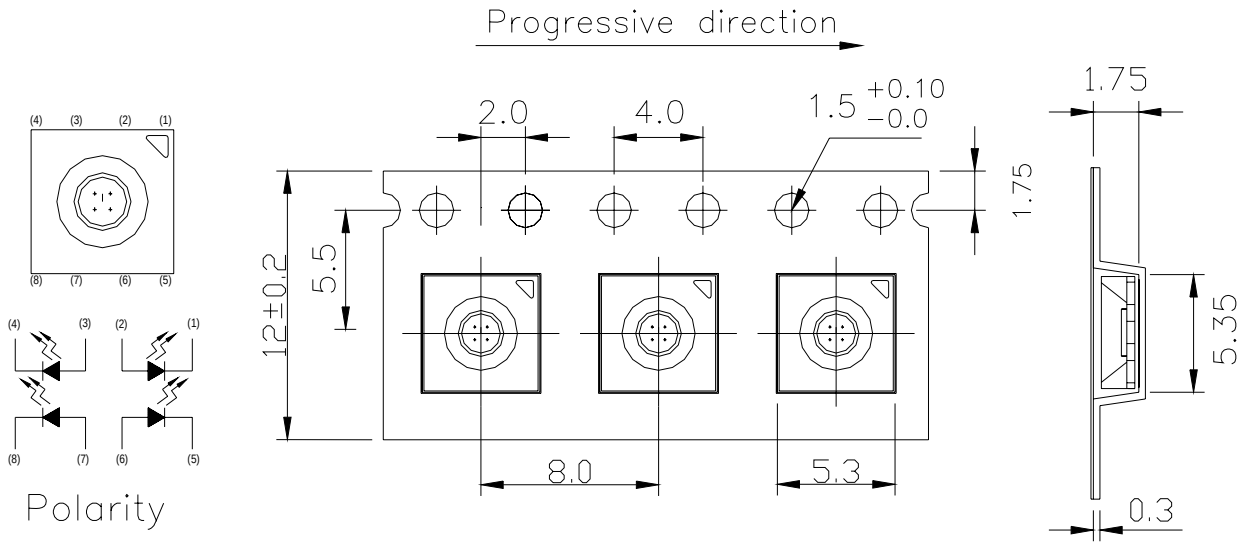
Carrier Tape Dimensions: Taping Quantity: 800pcs



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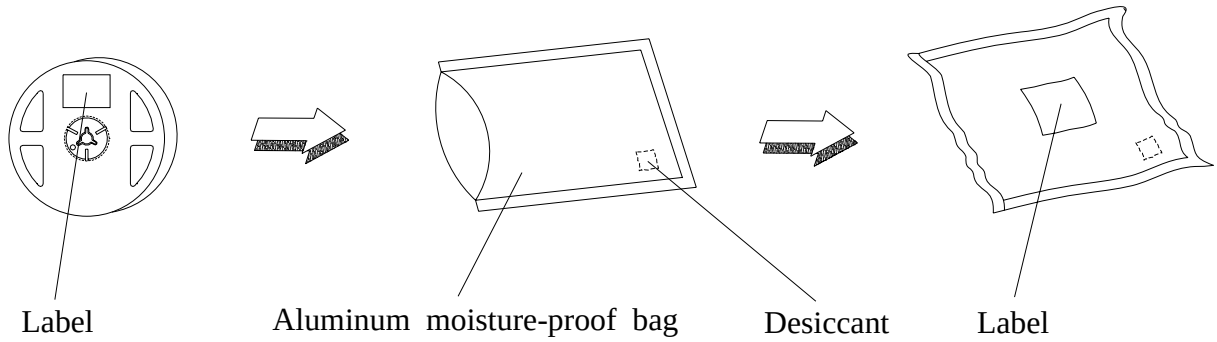
Moisture Resistant Packaging



Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.
Confidence level：90%
LTPD：10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃±5℃ Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100℃	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I_F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85℃/ 85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use

1. Over-current-proof

   Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

   2.1 Do not open moisture proof bag before the products are ready to use.

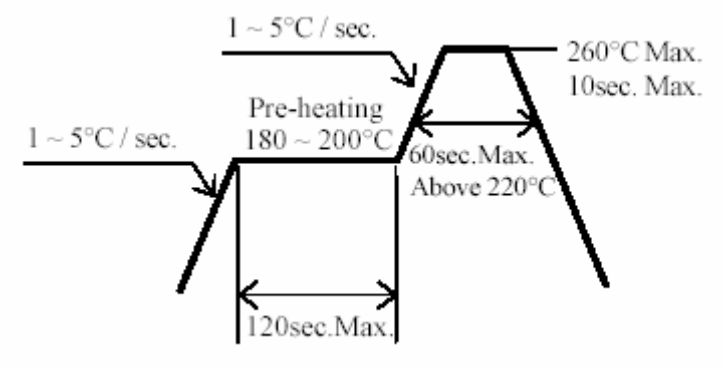
   2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.

   2.3 After opening the package: The LED's floor life is 1 year under 30 deg C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

   2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
   Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

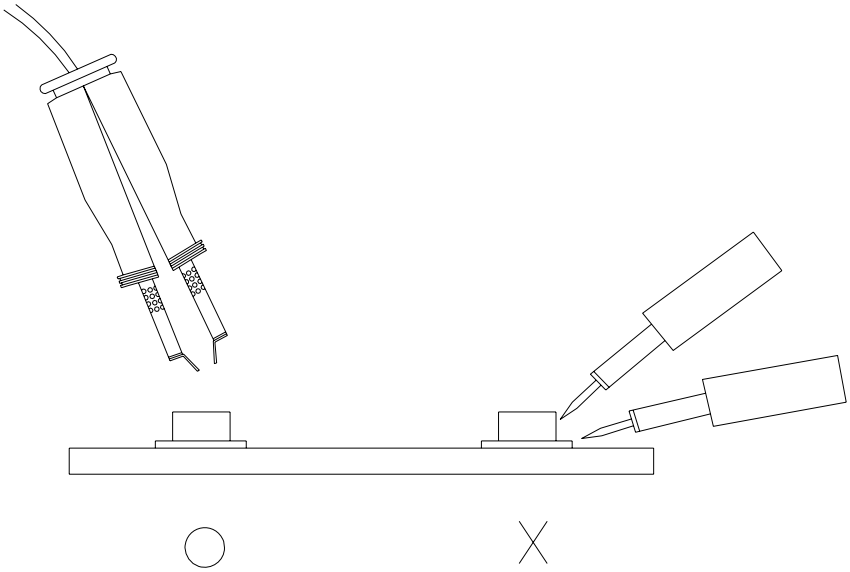
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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